

CLAIMS

1. A film carrier tape for mounting electronic devices thereon having a mounting unit in which a wiring pattern is
5 formed by etching on a base material,

wherein the mounting unit has a target mark to be a reference of an alignment for carrying out final defect marking in a target position on the mounting unit by marking means as a pattern formed on the base material by
10 the etching.

2. The film carrier tape for mounting electronic devices thereon according to claim 1, wherein the target mark is not electrically connected to the wiring pattern.

15

3. The film carrier tape for mounting electronic devices thereon according to claim 1, wherein the target mark is formed to be clearly indicated by a wiring shape of the wiring pattern.

20

4. The film carrier tape for mounting electronic devices thereon according to any of claims 1 to 3, wherein the target mark takes an almost identical shape to a marking shape of the marking means.

25

5. The film carrier tape for mounting electronic devices thereon according to claim 1, wherein the target mark is formed in an optional position A₂ on a base material which is placed apart from a target position A₁ for execution of
5 final defect marking and is not provided with a wiring pattern, and

an optional position A_{2'} on a base material which is not provided with the wiring pattern over a line which is perpendicular to a line connecting the positions A₁ and A₂
10 and passes through the position A₁ or a position A_{2''} which is not provided with the wiring pattern on a projection of the position A₂ with respect to the position A₁.

6. The film carrier tape for mounting electronic devices thereon according to any of claims 1 to 5, wherein the
15 mounting unit does not have a device hole.

7. An film carrier tape for mounting electronic devices thereon which has a plurality of mounting units provided
20 with a wiring pattern by etching on a base material and is subjected to a final defect marking step,

wherein the mounting units decided to be normal at a quality inspecting step have target marks formed in predetermined positions on the units as a pattern formed by
25 the etching so as to be a reference of an alignment for

carrying out final defect marking in target positions on the units by marking means if the units are decided to be defective at the quality inspecting step, and

the mounting units decided to be defective at the
5 quality inspecting step have final defect marking carried out in predetermined positions based on the target marks.

8. The film carrier tape for mounting electronic devices thereon according to claim 7, wherein the mounting unit
10 does not have a device hole.

9. A final defect marking method of a film carrier tape for mounting electronic devices thereon having a mounting unit provided with a wiring pattern by etching on a base material which serves to carry out final marking on the mounting unit decided to be defective at a quality inspecting step,

wherein defect marking is carried out in a marking position determined by aligning marking means with the
20 mounting unit based on a position of a target mark formed as a pattern on the base material by the etching.

10. The final defect marking method of a film carrier tape for mounting electronic devices thereon according to claim
25 9, wherein the mounting unit does not have a device hole.